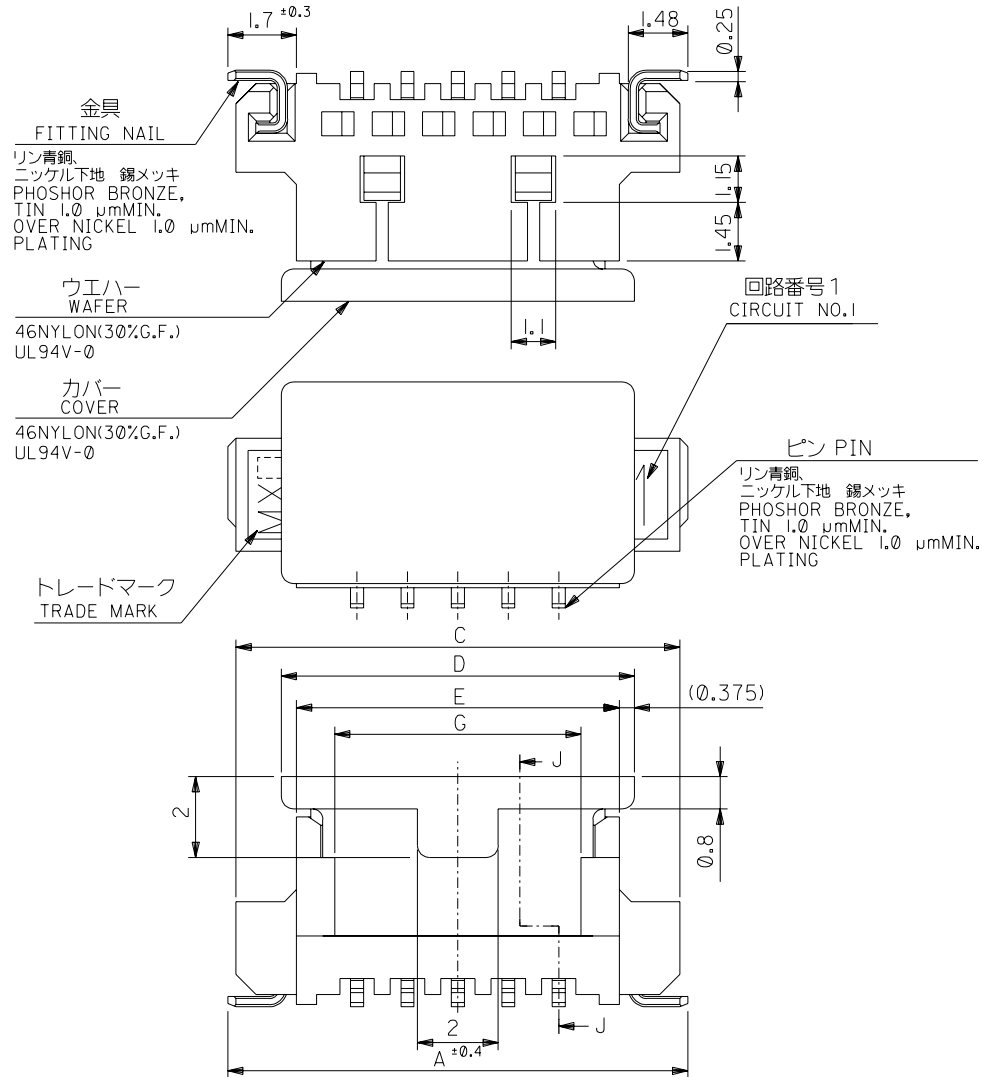
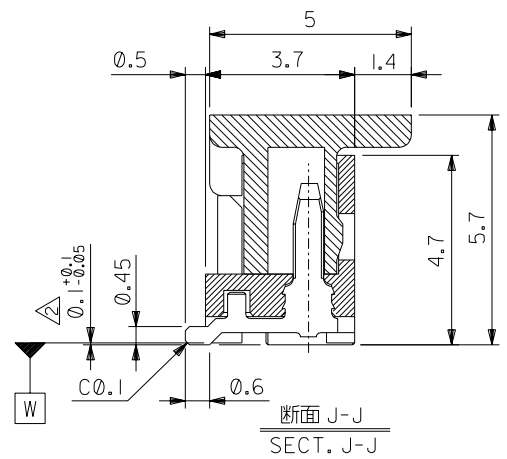


DWG. NO.
SD-53398-034



NOTES

1. 嵌合相手: 51021シリーズ MATE WITH: 51021 SERIES
2. 水平面上においての、ウエハー底面 [W] とソルダーテール及びフィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM [W]
3. 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**20 の鉛フリー品である。 THIS PRODUCT IS LEAD FREE OF 53398-**20.



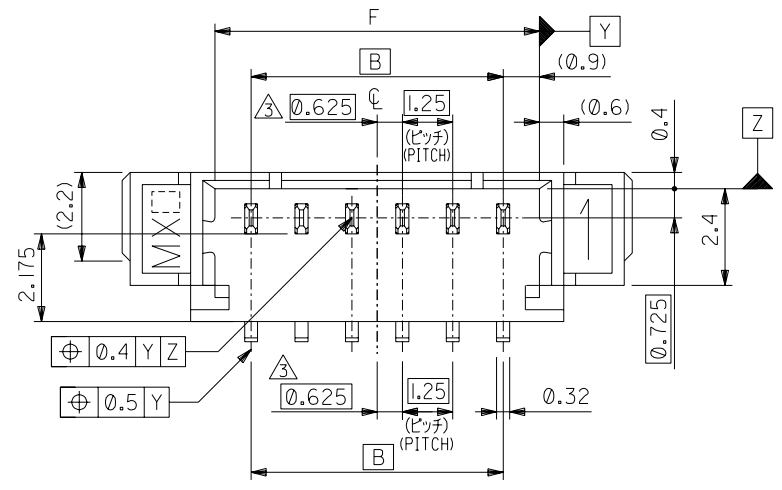
17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

DO NOT SCALE DRAWING

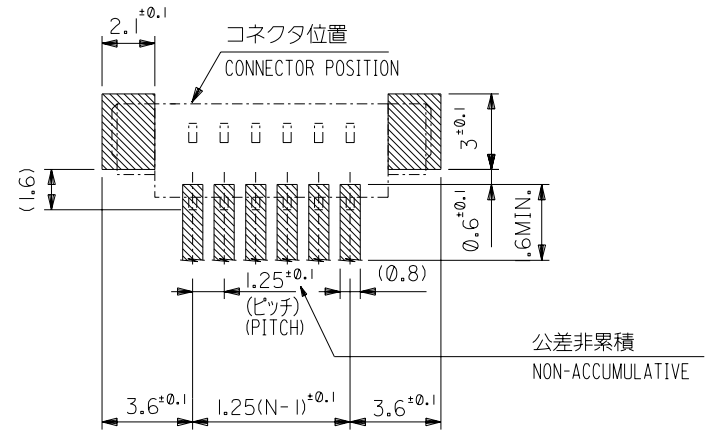
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	RELEASED '04/02/12	MATERIAL 材料 SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 ±0.2 10 OVER 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3	SCALE DESIGN UNITS THIRD ANGLE PROJECTION	MODEL NO. 53398-**29	DIMENSIONS: mm INCH mm INCH mm ONLY	SHT REV
					FINISH 仕上げ #		WIRE RANGE 適用電線範囲 #			TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
					INS. RANGE 被覆外径 #		ANGLE 角度 ±3°			MATERIAL NO. SD-53398-034.S01	DRAWING NO. SD-53398-034	SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.											SIZE B	

SD-53398-034.S01

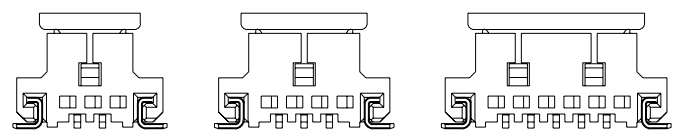
8 7 6 5 4 3 2 1



カバーなしの場合 (53398-**19)
IN CASE OF WITHOUT COVER



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2極 2 CKT.
3極 3 CKT.
4極以上 OVER 4 CKT.

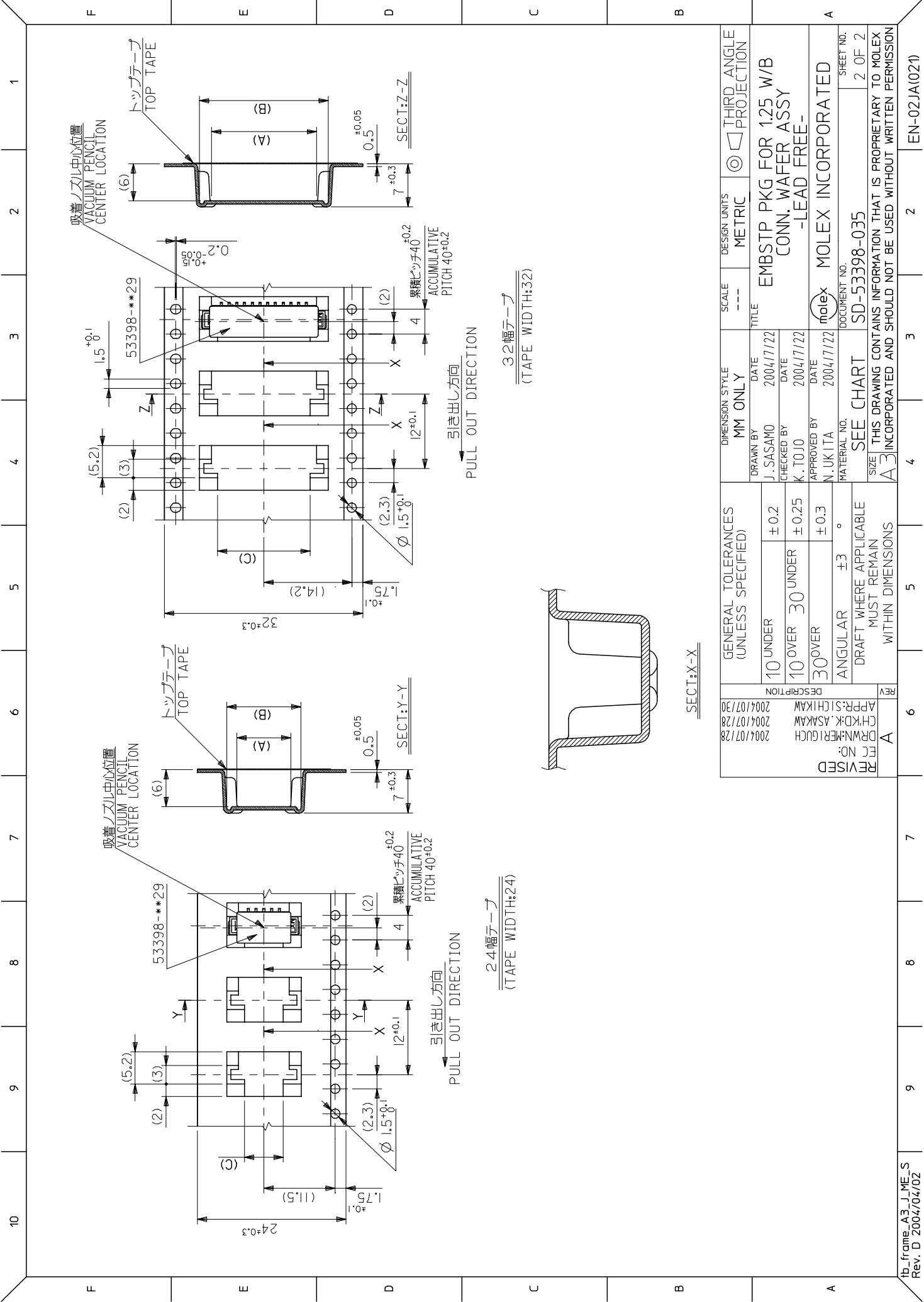
△ ロック形状図
LOCK CONFIGURATION

NOTES

△ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

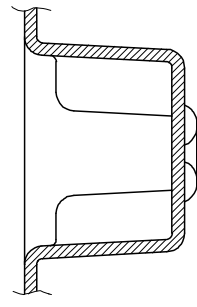
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	MODEL NO.	53398-**29	DIMENSIONS:	SHT	REV
							SEE NOTES	10 UNDER 未満 ±0.2	10 OVER 30 UNDER 未満 ±0.25	30 OVER 以上 ±0.3	DRAWN BY & DATE Y.SAKIYAMA '04/02/12	DESIGN UNITS mm □ INCH	THIRD ANGLE PROJECTION	mm □ INCH □ mm ONLY
							FINISH 仕上げ					TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
							WIRE RANGE 適用電線範囲					MOLEX INCORPORATED		
							INS. RANGE 被覆外径					MATERIAL NO.	DRAWING NO.	SHEET NO.
												SD-53398-034	SD-53398-034	2 OF 2
												THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		
												SIZE B		
												EN-02J(097) MXJ-54		

8 7 6 5 4 3 2 1



2.4幅テープ
(TAPE WIDTH:24)

3.2幅テープ
(TAPE WIDTH:32)



SECT: X-X

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
10 UNDER	± 0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-		
10 OVER	30 UNDER	CHECKED BY K. TOJO	DATE 2004/7/22	DOCUMENT NO. MOLEX INCORPORATED		
30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2004/7/22	SHEET NO. 2 OF 2		
ANGULAR	± 3 °	MATERIAL NO. SEE CHART		SD-53398-035		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
REVISED	EC NO.	DESCRIPTION		A3 INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
2004/07/28	2004/07/28	DRWN:MERI GUCH	2004/07/28	A3		
2004/07/28	2004/07/28	CHKD:K. ASAKAW	2004/07/28	A3		
2004/07/30	2004/07/30	APPR:SI CHIKAW	2004/07/30	A3		